

MITSUBISHI LSIs

MH1M09B2J-7,-8,-10/ MH1M09B2JA-7,-8,-10

STATIC COLUMN MODE 1048576-WORD BY 9-BIT DYNAMIC RAM

DESCRIPTION

The MH1M09B2J, JA is 1048576 word x 9 bit dynamic RAM and consists of nine industry standard 1M x 1 dynamic RAMs in SOJ.

The mounting of SOJ on a single in-line package provides any application where high densities and large quantities of memory are required.

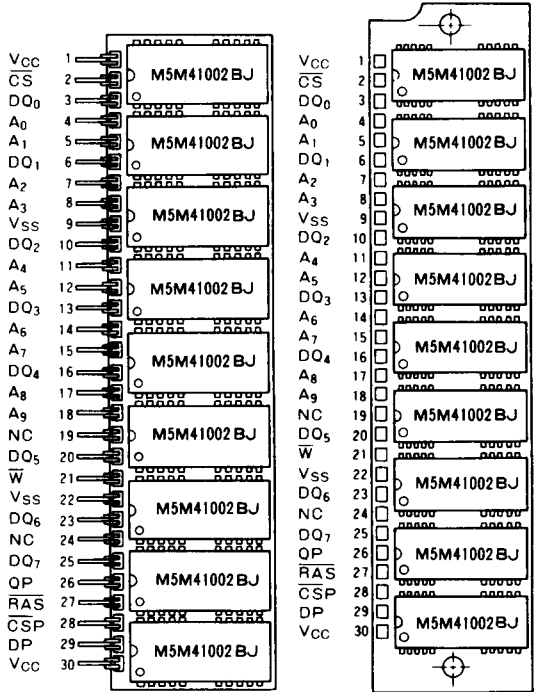
FEATURES

- Performance ranges

Type name	Access time (max) (ns)	Cycle time (min) (ns)	Power dissipation (typ) (mW)
MH1M09B2J-7 MH1M09B2JA-7	70	140	2070
MH1M09B2J-8 MH1M09B2JA-8	80	160	1800
MH1M09B2J-10 MH1M09B2JA-10	100	190	1575

- Utilizes industry standard 1M RAMs in SOJ
- 30 pins Single In-line Package
- Single +5V ($\pm 10\%$) supply operation
- Low standby power dissipation 24.8mW (max) CMOS input level
- Low operation power dissipation:
 - MH1M09B2J-7, MH1M09B2JA-7 . . . 3.96W (max)
 - MH1M09B2J-8, MH1M09B2JA-8 . . . 3.47W (max)
 - MH1M09B2J-10, MH1M09B2JA-10 . . . 2.97W (max)
- All inputs are directly TTL compatible
- All outputs are three-state and directly TTL compatible
- Includes (0.22 μ F x 9) decoupling capacitors
- 512 refresh cycles every 8ms, A₉ Pin is not need for refresh
- Common \overline{CS} control for eight common Data-In and Data-Out lines.
- Separate \overline{CS} (CSP) control for one separate pair of Data-In and Data-Out lines.
- The common I/O feature dictates the use of only early write operation to prevent contention on Data-In and

PIN CONFIGURATION (TOP VIEW)



Outline 30N5A (MH1M09B2JA) 30N9A (MH1M09B2J)
NC. NO CONNECTION

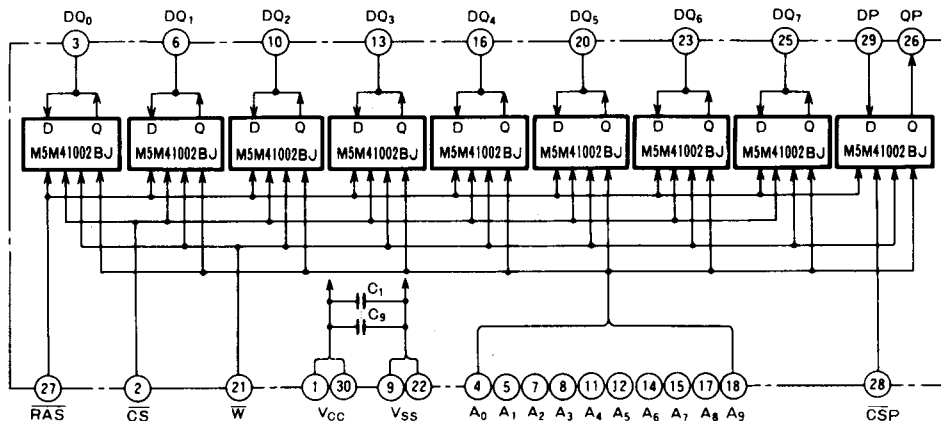
Data-Out.

- Bit nine (DP, QP) controlled by \overline{CSP} is generally used for parity.

APPLICATION

Main memory unit for computers, Refresh memory.

BLOCK DIAGRAM



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The MH1M09B2J, JA provide, in addition to normal read, and early write operations, a number of other functions, e.g., static Column mode. $\overline{\text{RAS}}$ -only refresh and $\overline{\text{CS}}$ before $\overline{\text{RAS}}$ refresh. This input conditions for each are shown in Table 1.

Table 1 Input conditions for each mode

Operation	Inputs					Input/Output		Refresh	Remark
	$\overline{\text{RAS}}$	$\overline{\text{CS}}$	$\overline{\text{W}}$	Row address	Column address	Input	Output		
Read	ACT	ACT	NAC	APD	APD	OPN	VLD	YES	Static column mode identical
Early write	ACT	ACT	ACT	APD	APD	VLD	OPN	YES	
$\overline{\text{RAS}}$ -only refresh	ACT	NAC	DNC	APD	DNC	DNC	OPN	YES	
Hidden refresh	ACT	ACT	DNC	DNC	DNC	OPN	VLD	YES	
$\overline{\text{CS}}$ before $\overline{\text{RAS}}$ refresh	ACT	ACT	DNC	DNC	DNC	DNC	OPN	YES	
Standby	NAC	DNC	DNC	DNC	DNC	DNC	OPN	NO	

Note ACT: active, NAC: nonactive, DNC: don't care, VLD: valid, APD: applied, OPN: open

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ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	conditions	Ratings	Unit
V _{CC}	Supply voltage	With respect to V _{SS}	-1~7	V
V _I	Input voltage		-1~7	V
V _O	Output voltage		-1~7	V
I _O	Output current		50	mA
P _d	Power dissipation	T _a = 25°C	9	W
T _{opr}	Operating temperature		0~70	°C
T _{stg}	Storage temperature		-40~120	°C

RECOMMENDED OPERATING CONDITIONS (T_a = 0~70°C, unless otherwise noted) (Note 1)

Symbol	Parameter	Limits			Unit
		Min	Nom	Max	
V _{CC}	Supply voltage	4.5	5	5.5	V
V _{SS}	Supply voltage	0	0	0	V
V _{IH}	High-level input voltage, all inputs	2.4		6.5	V
V _{IL}	Low-level input voltage all inputs	-1.0		0.8	V

Note 1: All voltage values are with respect to V_{SS}.

ELECTRICAL CHARACTERISTICS (T_a = 0~70°C, V_{CC} = 5V ± 10%, V_{SS} = 0V, unless otherwise noted) (Note 2)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
V _{OH}	High-level output voltage	I _{OH} = -5mA	2.4		V _{CC}	V
V _{OL}	Low-level output voltage	I _{OL} = 4.2mA	0		0.4	V
I _{OZ}	Off state output current	QP floating 0V ≤ V _{OUT} ≤ 5.5V	-20		20	μA
I _I	Input current	0V ≤ V _{IH} ≤ 6.5V, Other input pins = 0V	-90		90	μA
I _{CC1(AV)}	Average supply current from V _{CC} operating (Note 3, 4)	MH1M09B2-7			720	mA
		MH1M09B2-8			630	
		MH1M09B2-10			540	
I _{CC2}	Supply current from V _{CC} , standby	RAS = CS = V _{IH} , output open			18	mA
		RAS = CS ≥ V _{CC} - 0.5, output open			4.5	
I _{CC3(AV)}	Average supply current from V _{CC} refreshing (Note 3)	RAS cycling, CS = V _{IH}			720	mA
		t _{RC} = min, output open			630	
					540	
I _{CC6(AV)}	Average supply current from V _{CC} CS before RAS refresh mode (Note 3)	CS before RAS refresh cycling			720	mA
		t _{RC} = min, output open			630	
					540	
I _{CC7(AV)}	Average supply current from V _{CC} static column mode (Note 3, 4)	RAS = V _{IL} , CS = cycling			630	mA
		t _{SC} = min, output open			540	
					450	

Note 2: Current flowing into an IC is positive, out is negative.

3: I_{CC1(AV)}, I_{CC3(AV)}, I_{CC6(AV)} and I_{CC7(AV)} are dependent on cycle rate. Maximum current is measured at the fastest cycle rate.

4: I_{CC1(AV)} and I_{CC7(AV)} are dependent on output loading. Specified values are obtained with the output open.

CAPACITANCE (T_a = 0~70°C, V_{CC} = 5V ± 10%, V_{SS} = 0V, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit	
			Min	Typ	Max		
C _{I(A)}	Input capacitance, address inputs	V _I = V _{SS} f = 1MHz V _I = 25mVrms			60	pF	
C _{I(DQ)}	Data input/data output capacitance				17	pF	
C _{I(W)}	Input capacitance, write control input				75	pF	
C _{I(RAS)}	Input capacitance, RAS input				75	pF	
C _{I(CS)}	Input capacitance, CS input				70	pF	
C _{I(CSP)}	Input capacitance, CSP input				15	pF	
C _{I(OP)}	Input capacitance				15	pF	
C _{O(OP)}	Output capacitance		V _O = V _{SS} , f = 1MHz, V _I = 25mVrms			12	pF

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SWITCHING CHARACTERISTICS ($T_a = 0 \sim 70^\circ\text{C}$, $V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V$, unless otherwise noted) (Note 5)

Symbol	Parameter	Limits						Unit
		MH1M09B2-7		MH1M09B2-8		MH1M09B2-10		
		Min	Max	Min	Max	Min	Max	
t_{CAC}	Access time from \overline{CS} (Note 6, 7)		20		20		25	ns
t_{RAC}	Access time from \overline{RAS} (Note 6, 8)		70		80		100	ns
t_{CAA}	Column Address access time (Note 6, 9)		35		40		50	ns
t_{CLZ}	Output low impedance time from \overline{CS} low (Note 6)	5		5		5		ns
t_{OFF}	Output disable time after \overline{CS} high (Note 10)	0	20	0	20	0	25	ns

Note 5: An initial pause of 500 μ s is required after power-up followed by any 8 \overline{RAS} or $\overline{RAS}/\overline{CS}$ cycles before proper device operation is achieved.

Note that \overline{RAS} may be cycled during the initial pause. And any 8 \overline{RAS} or $\overline{RAS}/\overline{CS}$ cycles are required after prolonged periods of \overline{RAS} inactivity before proper device operation is achieved.

6: Measured with a load circuit equivalent to 2TTL loads and 100pF.

7: Assume that $t_{RCD} \geq t_{RCD(max)}$, $t_{RAD} \leq t_{RAD(max)}$.

8: Assume that $t_{RCD} \leq t_{RCD(max)}$, $t_{RAD} \leq t_{RAD(max)}$. If t_{RCD} or t_{RAD} is greater than $t_{RCD(max)}$ or $t_{RAD(max)}$ then t_{CAC} will increase by the amount that t_{RCD} or t_{RAD} exceeds $t_{RCD(max)}$ or $t_{RAD(max)}$.

9: Assume that $t_{RCD} - t_{RAD} \leq t_{CAA(max)} - t_{CAC(max)}$, and $t_{RCD} \geq t_{RCD(max)}$.

10: $t_{OFF(max)}$ defines the time at which the output achieves the high impedance state ($I_{OUT} \leq (\pm 10\mu\text{A})$) and is not reference to $V_{OH(min)}$ or $V_{OL(max)}$.

TIMING REQUIREMENTS (For Read, Write, Static Column Cycles)

($T_a = 0 \sim 70^\circ\text{C}$, $V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V$, unless otherwise noted, See notes 11, 12)

Symbol	Parameter	Limits						Unit
		MH1M09B2-7		MH1M09B2-8		MH1M09B2-10		
		Min	Max	Min	Max	Min	Max	
t_{REF}	Refresh cycle time		8		8		8	ms
t_{RP}	\overline{RAS} high pulse width	60		70		80		ns
t_{RCD}	Delay time, \overline{RAS} low to \overline{CS} low (Note 13)	20	50	25	60	25	75	ns
t_{CRP}	Delay time, \overline{CS} high to \overline{RAS} low (Note 14)	10		10		10		ns
t_{CPN}	\overline{CAS} high pulse width (Note 15)	30		35		35		ns
t_{RAD}	Column address delay time from \overline{RAS} low (Note 16)	15	35	20	40	20	50	ns
t_{ASR}	Row address setup time before \overline{RAS} low	0		0		0		ns
t_{ASC}	Column address setup time before \overline{CS} low or \overline{W} low	0		0		0		ns
t_{RAH}	Row address hold time after \overline{RAS} low	10		15		15		ns
t_{CAH}	Column address hold time after \overline{CS} low or \overline{W} low	15		20		20		ns
t_T	Transition time (Note 17)	3	50	3	50	3	50	ns

Note 11: The timing requirements are assumed $t_T = 5\text{ns}$.

12: $V_{IH(min)}$ and $V_{IL(max)}$ are reference levels for measuring timing of input signals.

13: $t_{RCD(max)}$ is specified as a reference point only. If t_{RCD} is less than $t_{RCD(max)}$, access time is t_{CAC} . If t_{RCD} is greater than $t_{RCD(max)}$, access time is $t_{RCD} + t_{CAC}$. $t_{RCD(min)}$ is specified as $t_{RCD(min)} = t_{RAH(min)} + 2t_T + t_{ASC(min)}$.

14: t_{CRP} requirement is applicable for all $\overline{RAS}/\overline{CS}$ cycles.

15: $t_{CPN(min)}$ is specified as $t_{CPN(min)} = t_{RCD(min)} + t_{CRP(min)}$ except for t_{CP} of static column mode cycle.

16: $t_{RAD(max)}$ is specified as a reference point only. If $t_{RAD} \geq t_{RAD(max)}$, access time is assumed by t_{CAA} for read cycle.

17: t_T is measured between $V_{IH(min)}$ and $V_{IL(max)}$.

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Read and Refresh Cycles

Symbol	Parameter	Limits						Unit
		MH1M09B2-7		MH1M09B2-8		MH1M09B2-10		
		Min	Max	Min	Max	Min	Max	
t _{RC}	Read cycle time	140		160		190		ns
t _{RAS}	\overline{RAS} low pulse width	70	10000	80	10000	100	10000	ns
t _{CS}	\overline{CS} low pulse width	20	10000	20	10000	25	10000	ns
t _{CSH}	\overline{CS} hold time after \overline{RAS} low	70		80		100		ns
t _{RSH}	\overline{RAS} hold time after \overline{CS} low	20		20		25		ns
t _{RCS}	Read setup time before \overline{CS} low	0		0		0		ns
t _{RCH}	Read hold time after \overline{CS} high (Note 18)	10		10		10		ns
t _{RRH}	Read hold time after \overline{RAS} high (Note 18)	10		10		10		ns
t _{RAL}	Column address to \overline{RAS} setup time	35		40		50		ns
t _{AH}	Column address hold time after \overline{RAS} high	10		10		10		ns
t _{RPC}	Precharge to \overline{CS} active time	0		0		0		ns

Note 18: Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.

Write Cycle

Symbol	Parameter	Limits						Unit
		MH1M09B2-7		MH1M09B2-8		MH1M09B2-10		
		Min	Max	Min	Max	Min	Max	
t _{WC}	Write cycle time	140		160		190		ns
t _{RAS}	\overline{RAS} low pulse width	70	10000	80	10000	100	10000	ns
t _{CS}	\overline{CS} low pulse width	20	10000	20	10000	25	10000	ns
t _{CSH}	\overline{CS} hold time after \overline{RAS} low	70		80		100		ns
t _{RSH}	\overline{RAS} hold time after \overline{CS} low	20		20		25		ns
t _{WCS}	Write setup time before \overline{CS} low (Note 19)	0		0		0		ns
t _{WCH}	Write hold time after \overline{CS} low	15		15		20		ns
t _{WH}	Write command hold time for output disable	0		0		0		ns
t _{WP}	Write pulse width	15		15		20		ns
t _{DS}	Data setup time	0		0		0		ns
t _{DH}	Data hold time after \overline{CS} low	15		15		20		ns

Note 19: When t_{WCS} < t_{WCS(min)}, Data input will contend with the data output because of the common I/O feature.

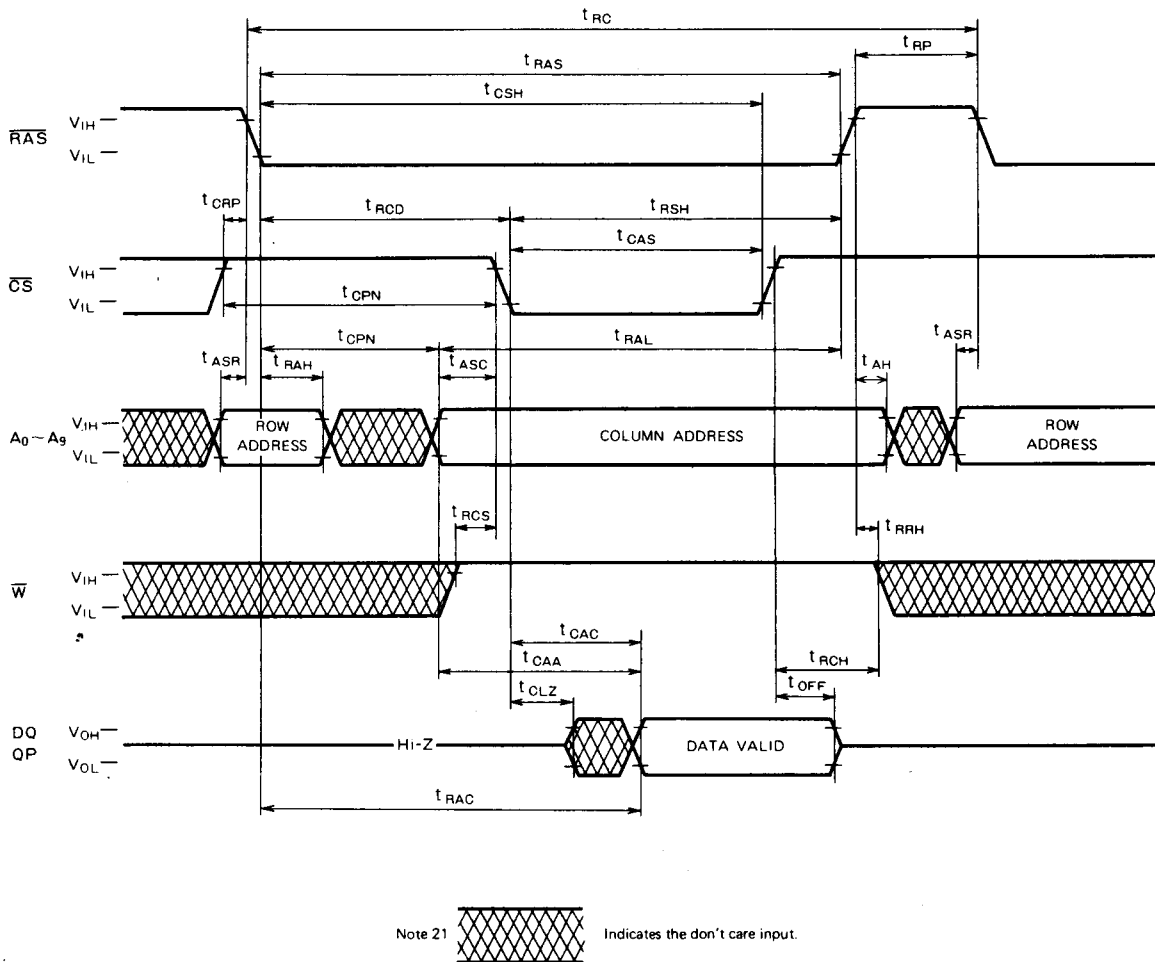
Static Column Mode Cycle (Read, Early Write Cycle)

Symbol	Parameter	Limits						Unit
		MH1M09B2-7		MH1M09B2-8		MH1M09B2-10		
		Min	Max	Min	Max	Min	Max	
t _{RSC}	SC read cycle time	40		45		55		ns
t _{WSC}	SC write cycle time	40		45		55		ns
t _{RAS}	\overline{RAS} low pulse width	110	100000	125	100000	155	100000	ns
t _{CS}	\overline{CS} low pulse width	20	10000	20	10000	25	10000	ns
t _{CP}	\overline{CS} high pulse width	10		10		10		ns
t _{WI}	Write invalid time	10		10		10		ns
t _{WH}	Write command hold time for output disable	0		0		0		ns
t _{AOH}	Data hold time from address change	10		10		10		ns

\overline{CS} before \overline{RAS} Refresh Cycle (Note 20)

Symbol	Parameter	Limits						Unit
		MH1M09B2-7		MH1M09B2-8		MH1M09B2-10		
		Min	Max	Min	Max	Min	Max	
t _{CSR}	\overline{CS} setup time for \overline{CS} before \overline{RAS} refresh	10		10		10		ns
t _{CHR}	\overline{CS} hold time for \overline{CS} before \overline{RAS} refresh	15		15		20		ns
t _{RPC}	Precharge to \overline{CS} active time	0		0		0		ns

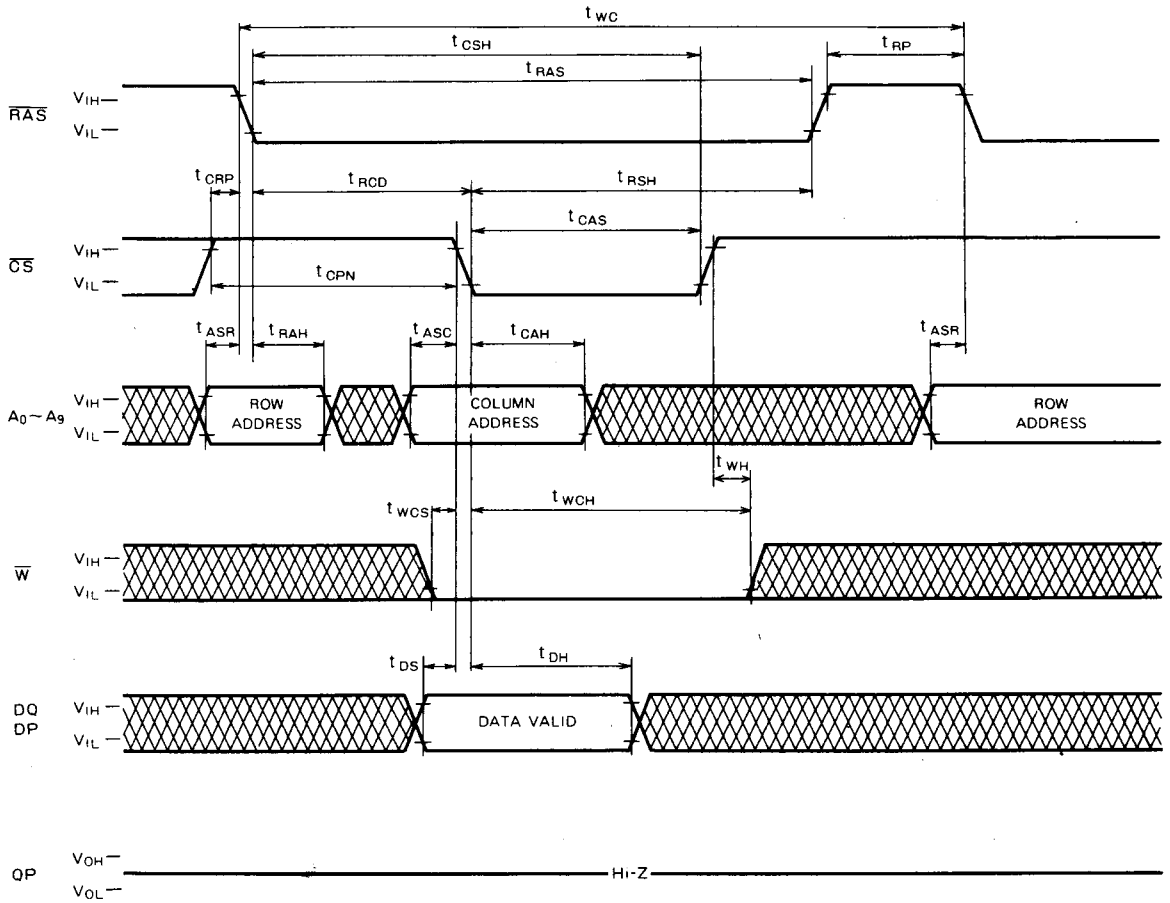
Note 20: Eight or more \overline{CS} before \overline{RAS} cycles are necessary for proper operation of \overline{CS} before \overline{RAS} refresh mode.

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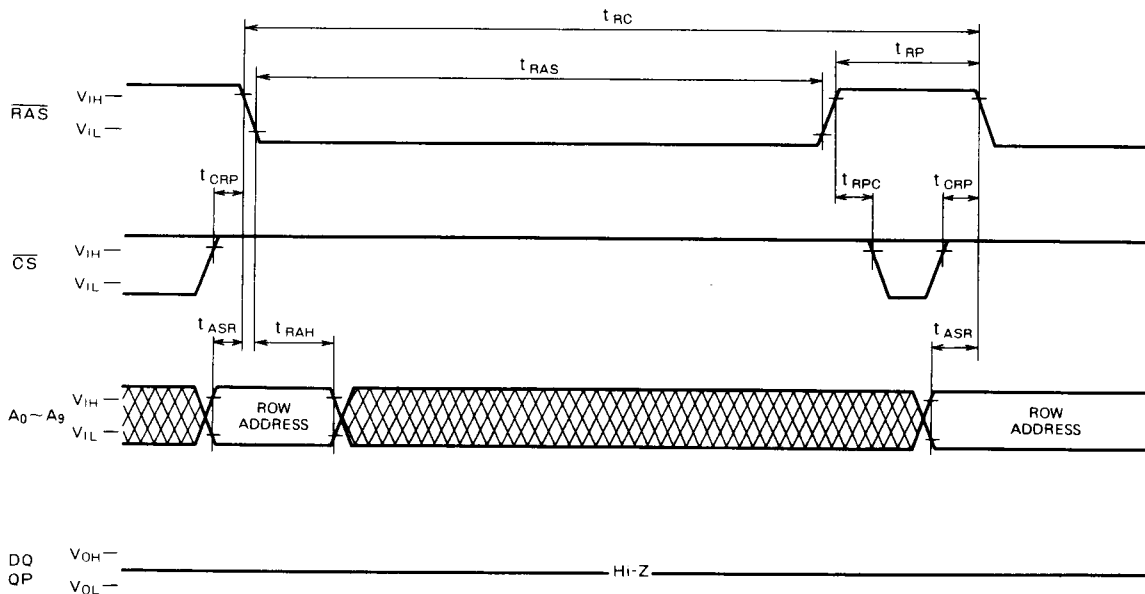
Early Write Cycle



MH1M09B2J-7,-8,-10/MH1M09B2JA-7,-8,-10

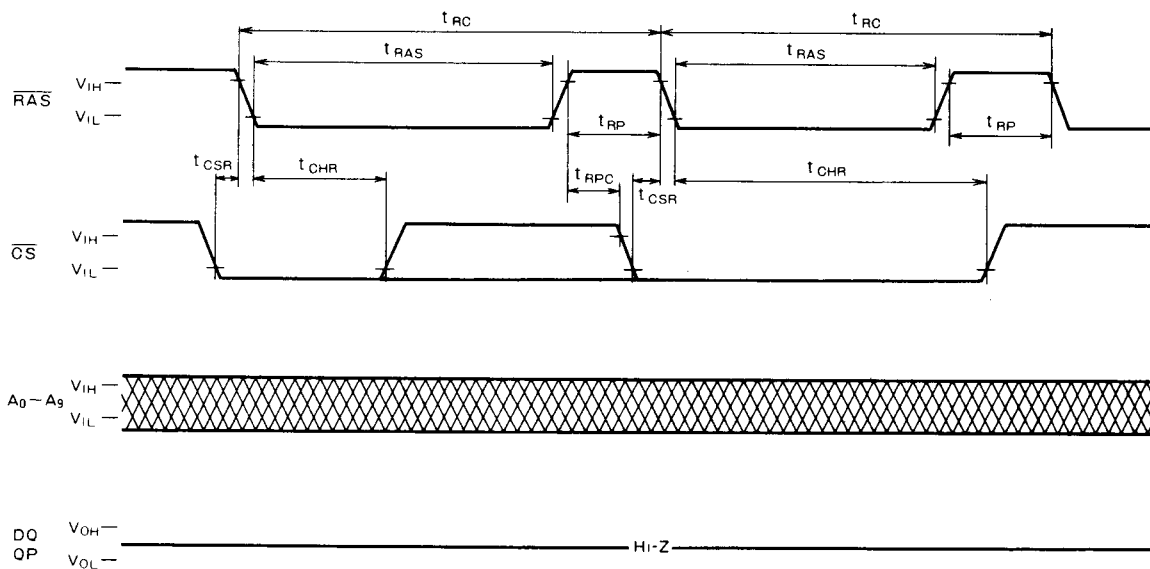
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RAS only Refresh Cycle (Note 22)



Note 22: \bar{W} , DP = don't care, A_9 may be V_{IH} or V_{IL} .

CS before RAS Refresh Cycle (Note 23)

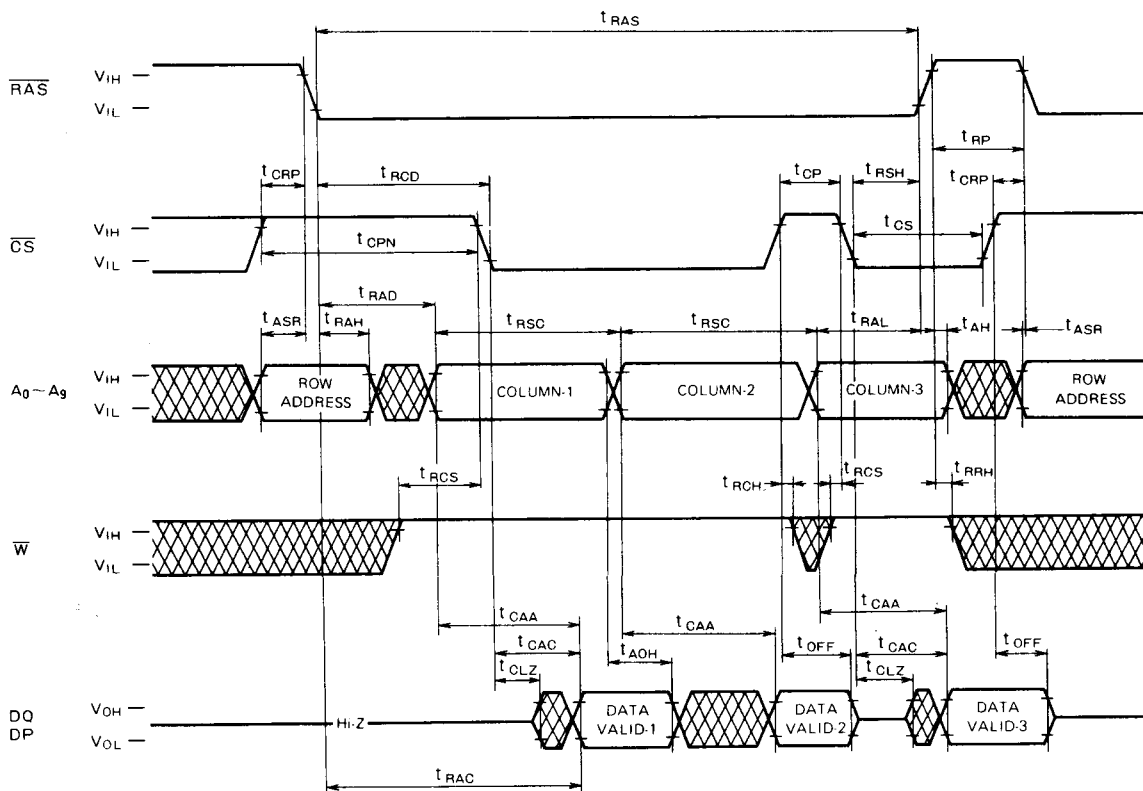


Note 23: \bar{W} , DP = don't care

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Static Column Mode Read Cycle



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Static Column Mode Early Write Cycle

